MA2S101

Silicon epitaxial planar type

For switching circuits

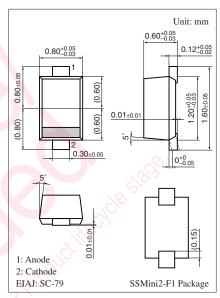
■ Features

- High breakdown voltage: $V_R = 250 \text{ V}$
- Small terminal capacitance C_t
- Suitable for high-density mounting

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	250	V
Repetitive peak reverse voltage	V _{RRM}	250	V
Forward current	I_{F}	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I _{FSM}	500	mA
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s



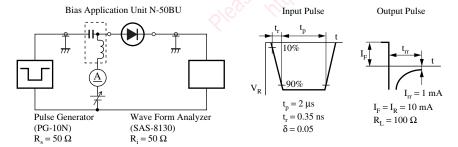
Marking Symbol: 1P

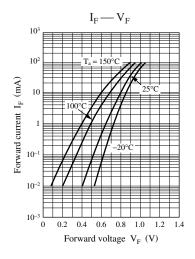
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

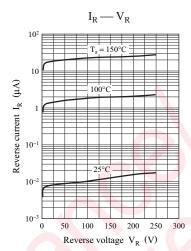
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	$I_F = 70 \text{ mA}$	90	950	1.2	V
Reverse current	I_R	$V_R = 250 \text{ V}$	0		1.0	μΑ
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$	0.7		3.0	pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$			60	ns
		$I_{rr} = 1 \text{ mA}$, $R_L = 100 \Omega$				

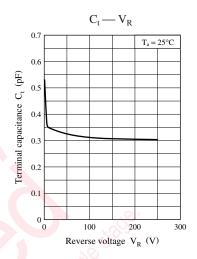
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 20 MHz.
- 3. *: t_{rr} measurement circuit









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